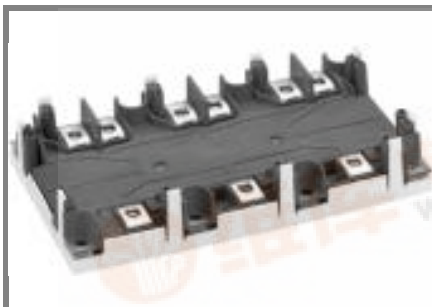


SKiM 400GD063D

SKiM[®] 5

IGBT Modules

SKiM 400GD063D

Preliminary Data

Features

- NPT-IGBT with positive temperature coefficient of V_{CEsat}
- Short circuit, self limiting to $6 \times I_C$
- DBC substrate : Al_2O_3
- Corresponds to standards IEC 60721-3-3 (humidity) class 3K7IE32 and IEC 68T.1 (climate) 40/125/56

Typical Applications

- Resonant inverters up to 100 kHz
- Inductive heating
- Electronic welder at $f_{sw} > 20$ kHz

Absolute Maximum Ratings

 $T_c = 25^\circ C$, unless otherwise specified

Symbol	Conditions	Values	Units
IGBT			
V_{CES}		600	V
I_C	$T_s = 25 (70)^\circ C$	420 (320)	A
I_{CM}	$T_s = 25 (70)^\circ C, t_p = 1$ ms	840 (640)	A
V_{GES}		± 20	V
$T_j (T_{stg})$		- 40 ... + 150 (125)	$^\circ C$
T_{cop}	max. case operating temperature		$^\circ C$
V_{isol}	AC, 1 min.	2500	V

Inverse diode

I_F	$T_s = 25 (70)^\circ C$	390 (260)	A
$I_{FM} = -I_{CM}$	$T_s = 25 (70)^\circ C, t_p = 1$ ms	840 (640)	A
I_{FSM}	$t_p = 10$ ms; sin.; $T_j = 150^\circ C$	4300	A

Characteristics

 $T_c = 25^\circ C$, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}; I_C = 12$ mA	4,5	5,5	6,5	V
I_{CES}	$V_{GE} = 0; V_{CE} = V_{CES}; T_j = 25 (125)^\circ C$			0,3	mA
V_{CEO}	$T_j = 25^\circ C$		0,9 (0,8)	1	V
r_{CE}	$T_j = 25 (125)^\circ C$		2 (2,9)	2,7	m Ω
V_{CEsat}	$I_C = 300$ A; $V_{GE} = 15$ V, $T_j = 25 (125)^\circ C$ on chip level		1,5 (1,7)	1,8	V
C_{ies}	$V_{GE} = 0; V_{CE} = 25$ V; $f = 1$ MHz		26,2		nF
C_{oes}	$V_{GE} = 0; V_{CE} = 25$ V; $f = 1$ MHz		3,7		nF
C_{res}	$V_{GE} = 0; V_{CE} = 25$ V; $f = 1$ MHz		3,6		nF
L_{CE}				20	nH
$R_{CC+EE'}$	resistance, terminal-chip $T_c = 25 (125)^\circ C$		0,9 (1,1)		m Ω
$t_{d(on)}$	$V_{CC} = 300$ V		160		ns
t_r	$I_C = 300$ A		120		ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 6,2 \Omega$		730		ns
t_f	$T_j = 125^\circ C$		60		ns
$E_{on} (E_{off})$	$V_{GE} \pm 15$ V		16 (16)		mJ
$E_{on} (E_{off})$	with SKHI 6; $T_j = 25^\circ C$ $V_{CC} = V; I_C = A$				mJ

Inverse diode

$V_F = V_{EC}$	$I_F = 300$ A; $V_{GE} = 0$ V; $T_j = 25 (125)^\circ C$	1,25 (1,2)	1,5		V
V_{TO}	$T_j = 25 (125)^\circ C$	0,85	0,9		V
r_T	$T_j = 25 (125)^\circ C$	1,3	2		m Ω
I_{RRM}	$I_F = 300$ A; $T_j = 125^\circ C$	220			A
Q_{rr}	$V_{GE} = 0$ V di/dt = 3000 A/ μ s	36,5			μ C
E_{rr}	$R_{Gon} = R_{Goff} = 6,2 \Omega$	7,3			mJ

Thermal characteristics

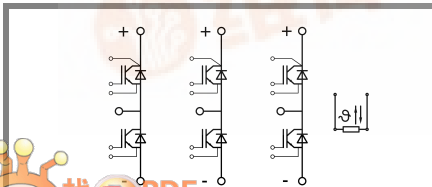
$R_{th(j-s)}$	per IGBT		0,13		K/W
$R_{th(j-s)}$	per FWD		0,19		K/W

Temperature Sensor

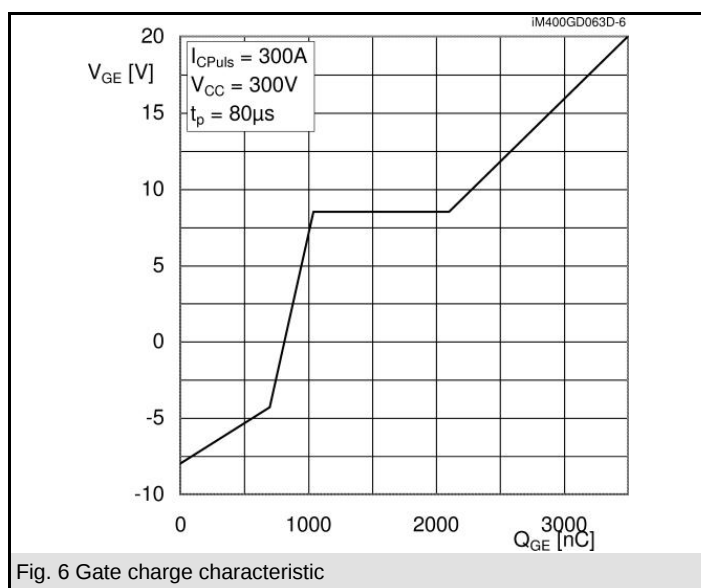
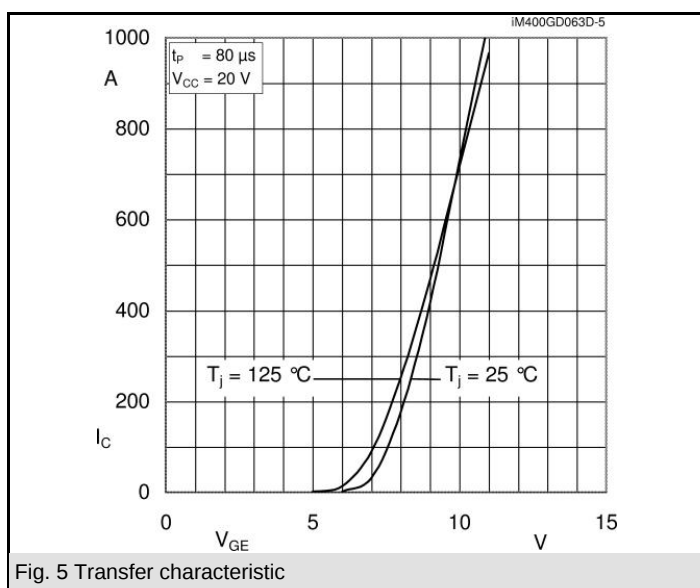
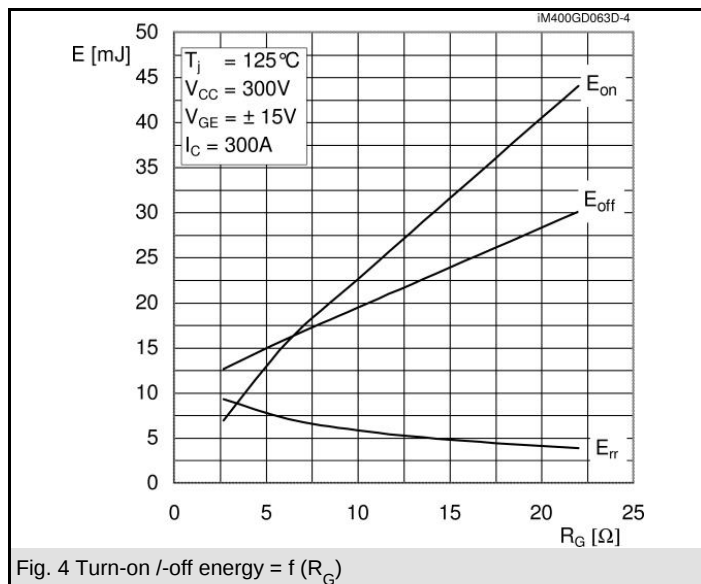
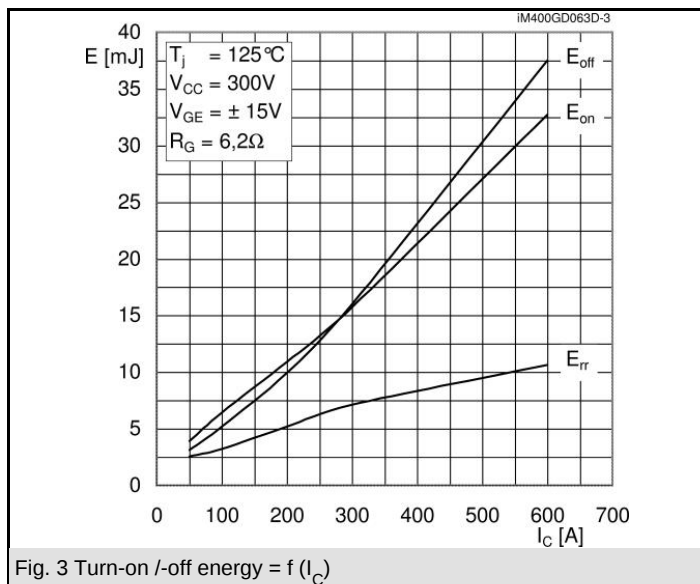
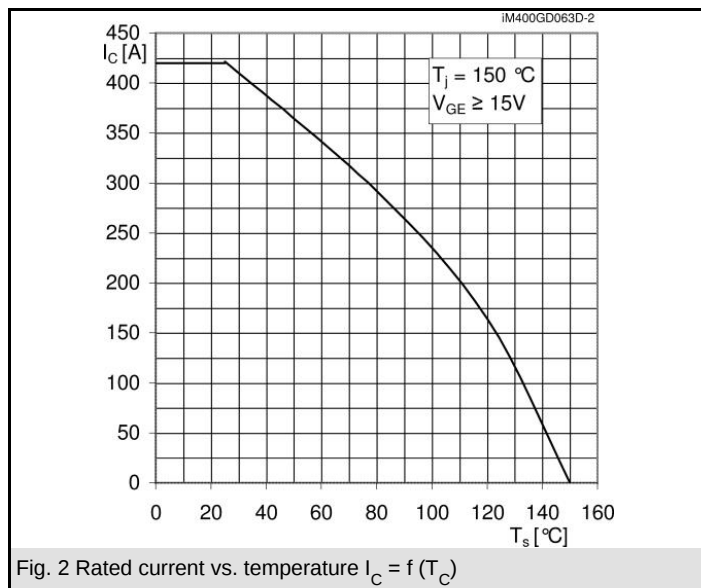
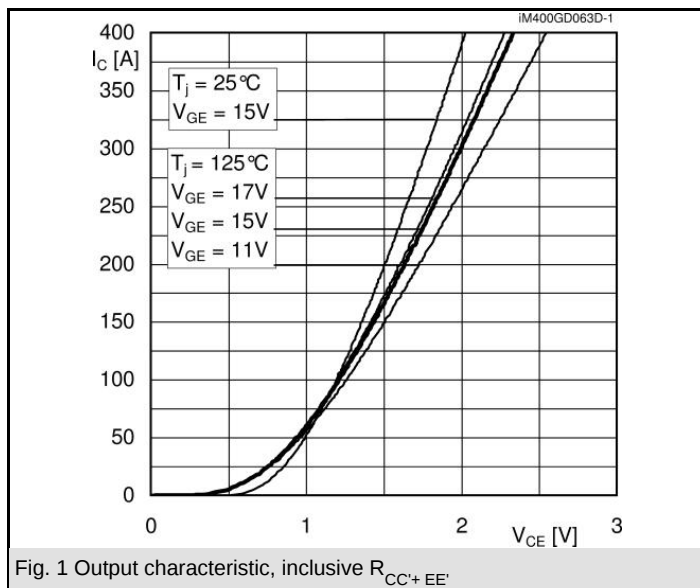
R_{TS}	$T = 25 (100)^\circ C$	1 (1,67)			k Ω
tolerance	$T = 25 (100)^\circ C$	3 (2)			%

Mechanical data

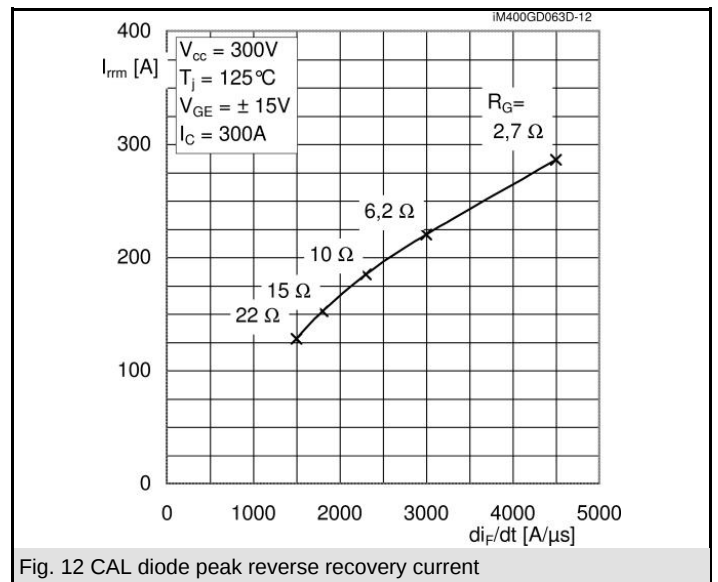
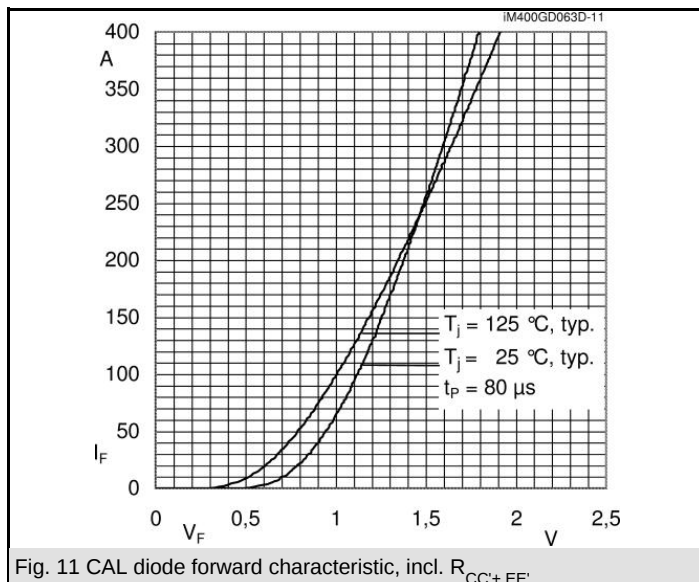
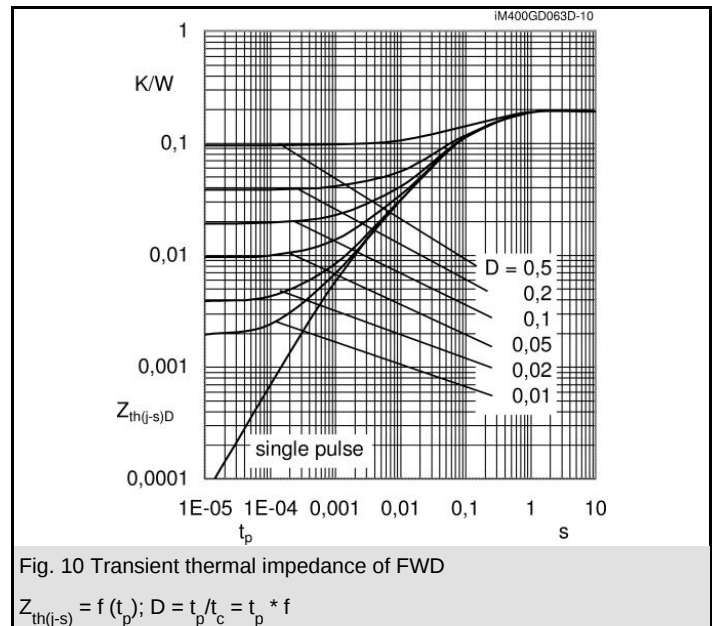
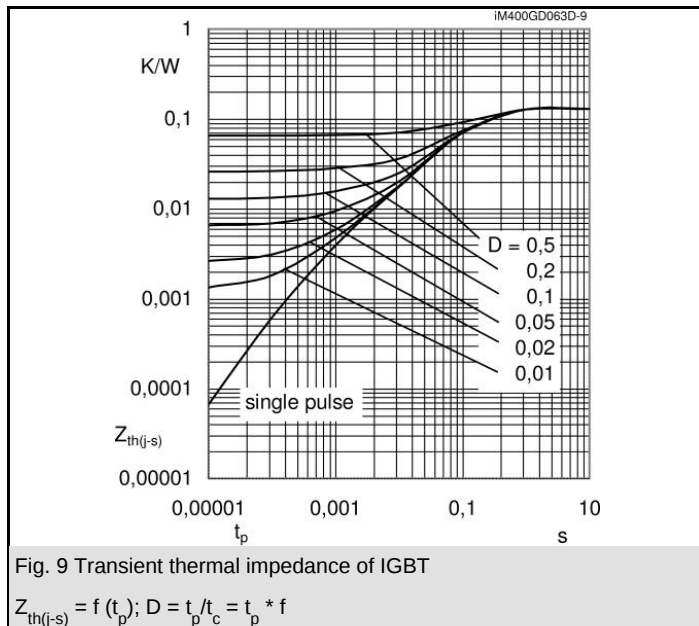
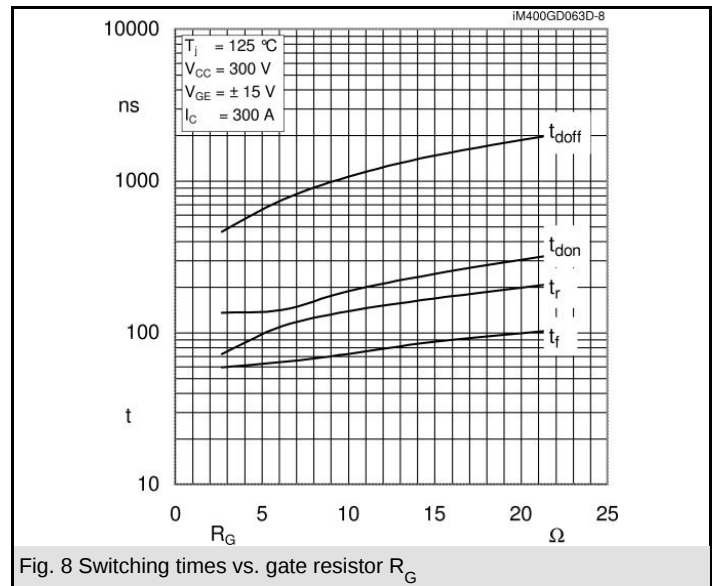
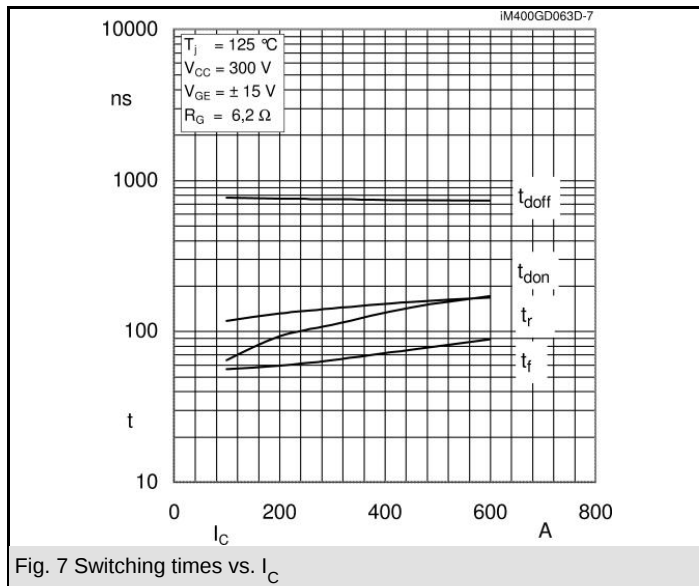
M_1	to heatsink (M5)	2	3		Nm
M_2	for terminals (M6)	4	5		Nm
w			325		g



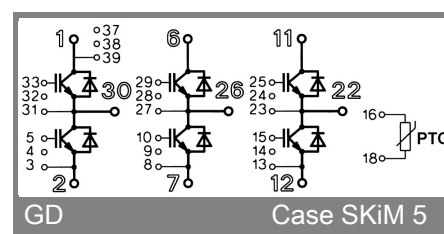
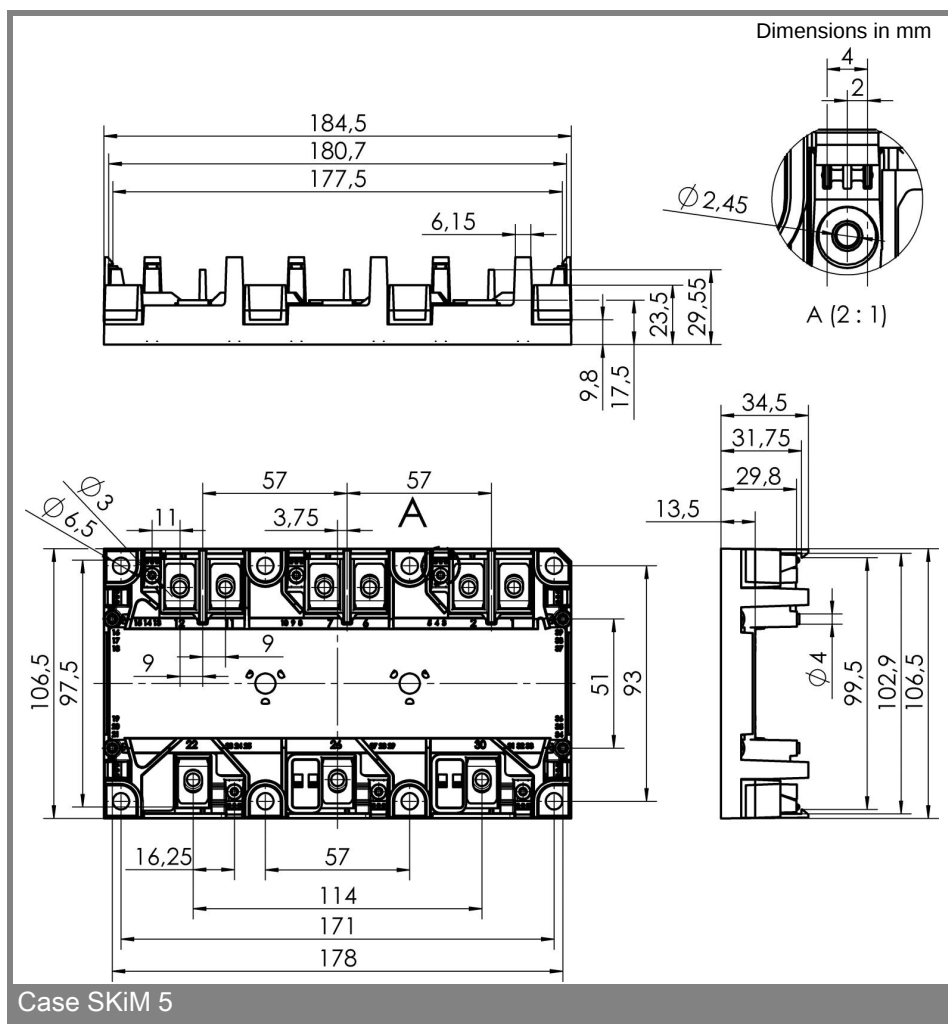
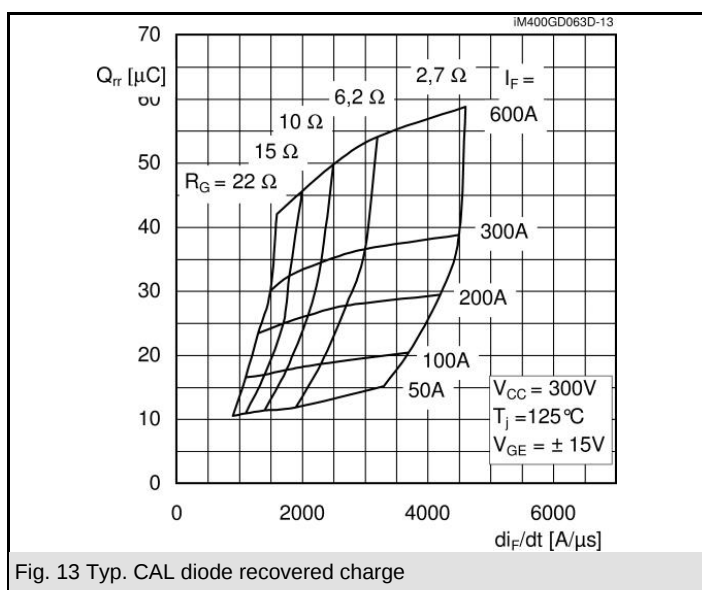
SKiM 400GD063D



SKiM 400GD063D



SKiM 400GD063D



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.